

# SN54HC4002, SN74HC4002 DUAL 4-INPUT POSITIVE-NOR GATES

SCLS157

D2684, DECEMBER 1982—REVISED SEPTEMBER 1987

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs

- Dependable Texas Instruments Quality and Reliability

## description

These devices contain two independent 4-input positive NOR gates. They perform the Boolean functions:

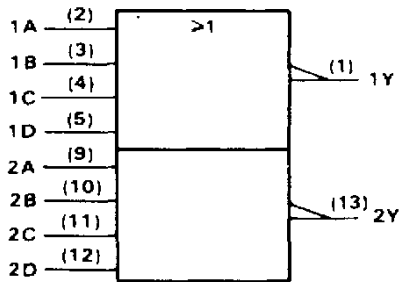
$Y = \overline{A + B + C + D}$  or  $Y = \overline{A} \cdot \overline{B} \cdot \overline{C} \cdot \overline{D}$   
in positive logic.

The SN54HC4002 is characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74HC4002 is characterized for operation from  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ .

FUNCTION TABLE

INPUTS				OUTPUT
A	B	C	D	Y
H	X	X	X	L
X	H	X	X	L
X	X	H	X	L
X	X	X	H	L
L	L	L	L	H

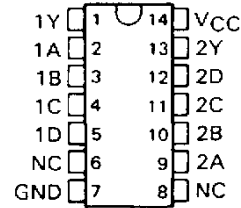
## logic symbol†



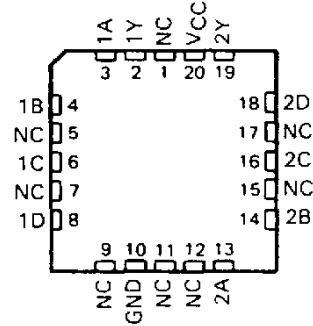
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, and N packages.

SN54HC4002 . . . J PACKAGE  
SN74HC4002 . . . D OR N PACKAGE  
(TOP VIEW)

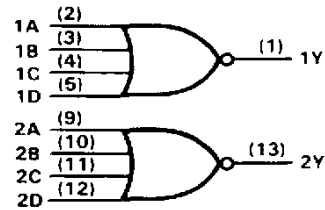


SN54HC4002 . . . FK PACKAGE  
(TOP VIEW)



NC—No internal connection

## logic diagram (positive logic)



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TEXAS  
INSTRUMENTS

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**SN54HC4002, SN74HC4002**  
**DUAL 4-INPUT POSITIVE-NOR GATES**

**absolute maximum ratings over operating free-air temperature range†**

Supply voltage range, $V_{CC}$ .....	-0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) .....	$\pm 20$ mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) .....	$\pm 20$ mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	$\pm 25$ mA
Continuous current through $V_{CC}$ or GND pins .....	$\pm 50$ mA
Lead temperature 1.6 mm (1/16 in) from case for 60 s: FK or J package .....	300°C
Lead temperature 1.6 mm (1/16 in) from case for 10 s: D or N package .....	260°C
Storage temperature range .....	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

**recommended operating conditions**

		SN54HC4002			SN74HC4002			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$	Supply voltage	2	5	6	2	5	6	V
$V_{IH}$	High-level input voltage	$V_{CC} = 2$ V	1.5		1.5			V
		$V_{CC} = 4.5$ V	3.15		3.15			
		$V_{CC} = 6$ V	4.2		4.2			
$V_{IL}$	Low-level input voltage	$V_{CC} = 2$ V	0	0.3	0	0.3		V
		$V_{CC} = 4.5$ V	0	0.9	0	0.9		
		$V_{CC} = 6$ V	0	1.2	0	1.2		
$V_I$	Input voltage	0		$V_{CC}$	0		$V_{CC}$	V
$V_O$	Output voltage	0		$V_{CC}$	0		$V_{CC}$	V
$t_t$	Input transition (rise and fall) times	$V_{CC} = 2$ V	0	1000	0	1000		ns
		$V_{CC} = 4.5$ V	0	500	0	500		
		$V_{CC} = 6$ V	0	400	0	400		
$T_A$	Operating free-air temperature	-55		125	-40		85	°C

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	$V_{CC}$	$T_A = 25^\circ\text{C}$			SN54HC4002		SN74HC4002		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$V_{OH}$	$V_I = V_{IH}$ or $V_{IL}$ , $I_{OH} = -20 \mu\text{A}$	2 V	1.9	1.998		1.9		1.9	V	
		4.5 V	4.4	4.499		4.4		4.4		
		6 V	5.9	5.999		5.9		5.9		
	4.5 V	3.98	4.30		3.7		3.84			
$V_{OL}$	$V_I = V_{IH}$ or $V_{IL}$ , $I_{OL} = 20 \mu\text{A}$	2 V		0.002	0.1		0.1		V	
		4.5 V		0.001	0.1		0.1			
		6 V		0.001	0.1		0.1			
	4.5 V		0.17	0.26		0.4		0.33		
$I_I$	$V_I = V_{CC}$ or 0	6 V		$\pm 0.1$	$\pm 100$		$\pm 1000$		$\mu\text{A}$	
		6 V			2		40		20	
$I_{CC}$	$V_I = V_{CC}$ or 0, $I_O = 0$	6 V							$\mu\text{A}$	
$C_i$		2 to 6 V		3	10		10		10	pF



**SN54HC4002, SN74HC4002**  
**DUAL 4-INPUT POSITIVE-NOR GATES**

switching characteristics over recommended operating free-air temperature range (unless otherwise noted),  $C_L = 50$  pF (see Note 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54HC4002		SN74HC4002		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A thru D	Y	2 V		44	110		165		140	ns
			4.5 V		12	22		33		28	
			6 V		11	19		28		24	
t <sub>t</sub>		Y	2 V		38	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	

C <sub>pd</sub>	Power dissipation capacitance per gate	No load, T <sub>A</sub> = 25°C	25 pF typ
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Note 1: Load circuits and voltage waveforms are shown in Section 1.



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**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
84044012A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	84044012A SNJ54HC 4002FK	<a href="#">Samples</a>
8404401CA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8404401CA SNJ54HC4002J	<a href="#">Samples</a>
JM38510/65104BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 65104BCA	<a href="#">Samples</a>
M38510/65104BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 65104BCA	<a href="#">Samples</a>
SN54HC4002J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54HC4002J	<a href="#">Samples</a>
SNJ54HC4002FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	84044012A SNJ54HC 4002FK	<a href="#">Samples</a>
SNJ54HC4002J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8404401CA SNJ54HC4002J	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
84044012A	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54HC4002FK	FK	LCCC	20	55	506.98	12.06	2030	NA

## GENERIC PACKAGE VIEW

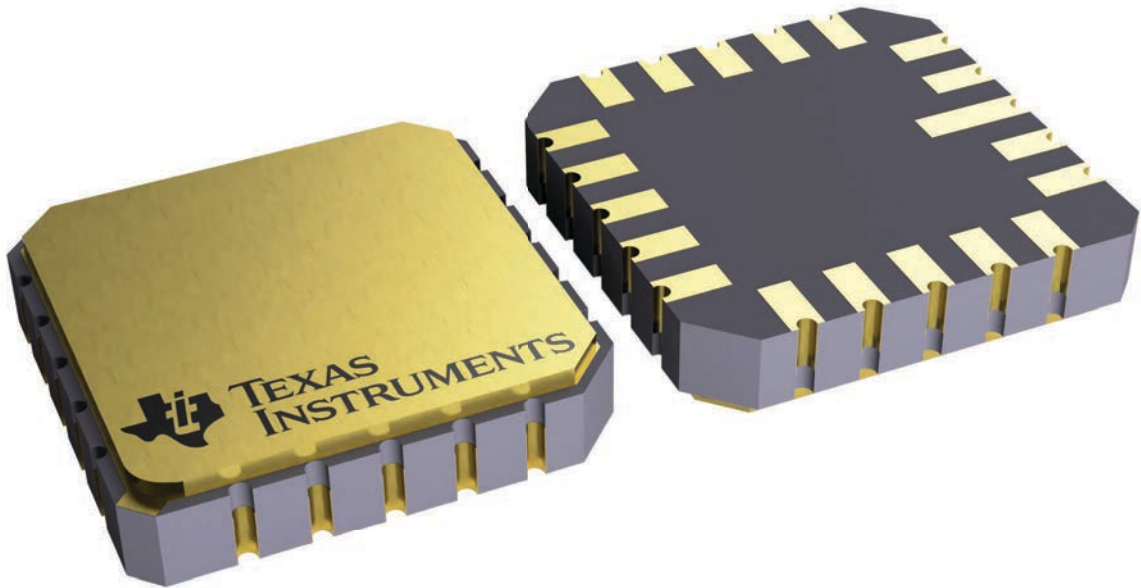
**FK 20**

**LCCC - 2.03 mm max height**

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4229370VA\

J 14

**GENERIC PACKAGE VIEW**  
**CDIP - 5.08 mm max height**  
CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040083-5/G



# J0014A



## PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



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### NOTES:

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

# EXAMPLE BOARD LAYOUT

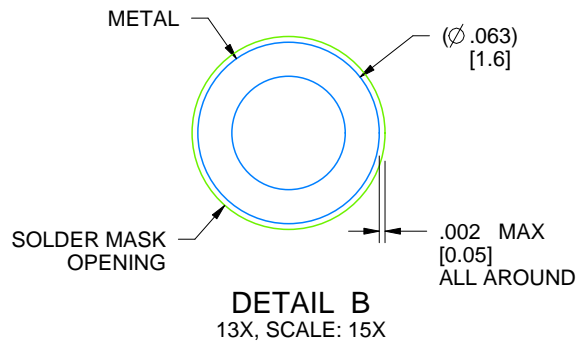
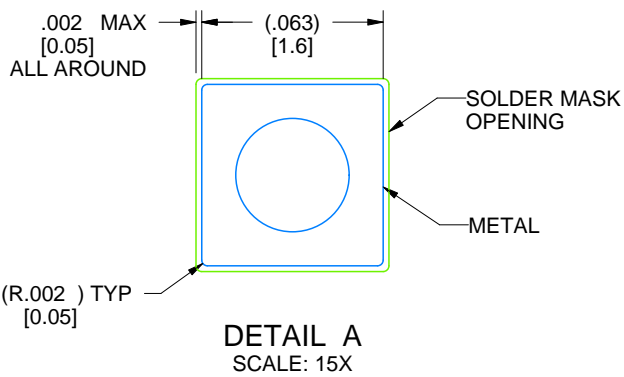
J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE: 5X



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